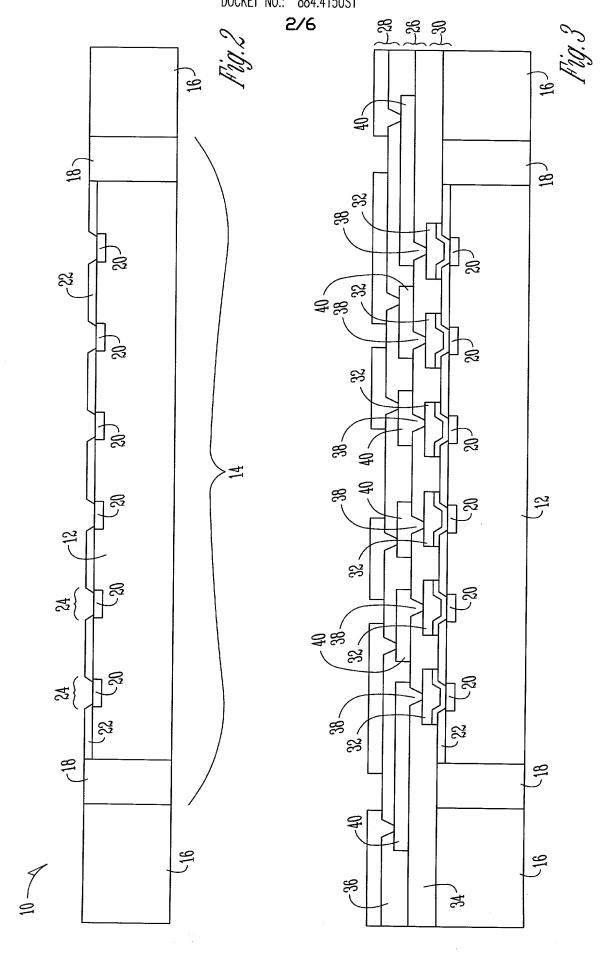


Fig. 1

TITLE: POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR USE IN MICROELECTRONIC CIRCUIT PACKAGING INVENTORS NAME: Steven Towle DOCKET NO.: 884.415US1



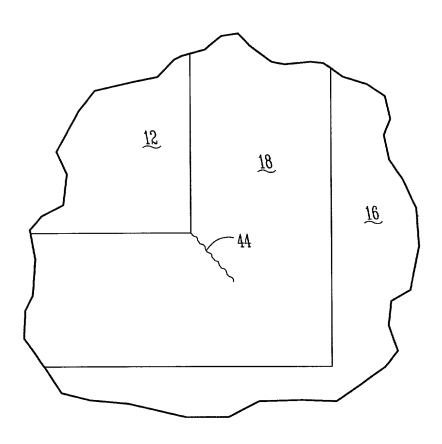


Fig. 4

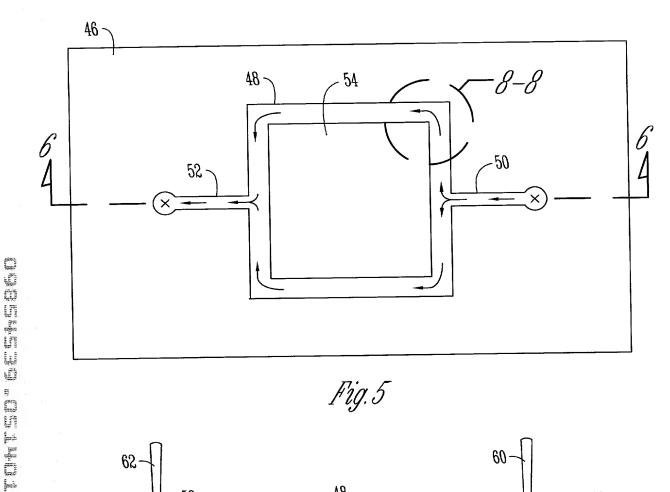


Fig. 5

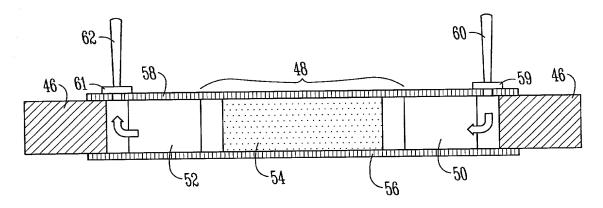
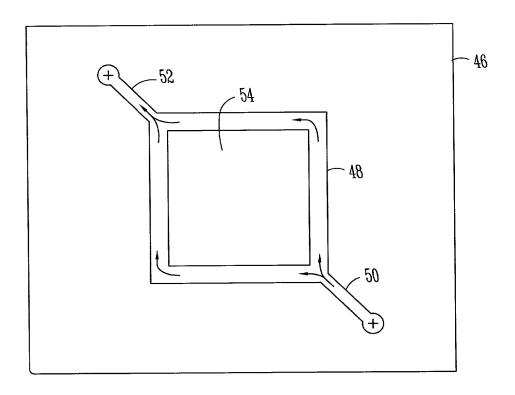
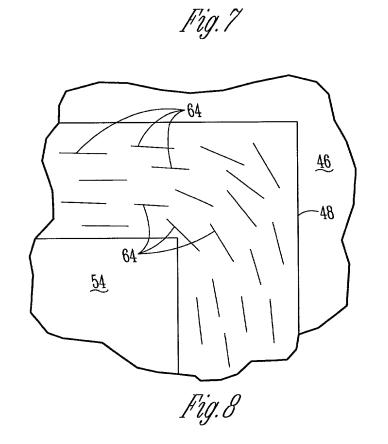


Fig. 6





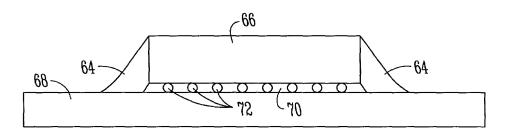
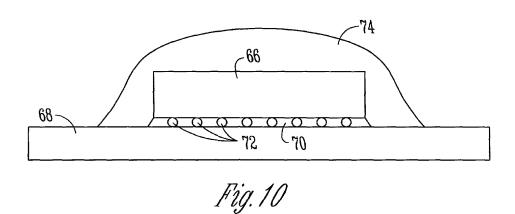


Fig. 9



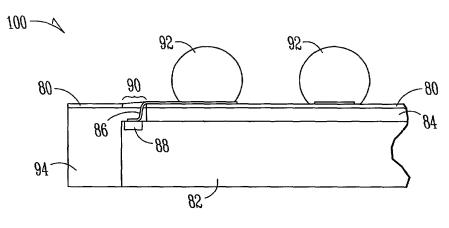


Fig. 11